



## **CyberOptics Showcases Large Particle Sensing Functionality in Next-Generation Airborne Particle Sensors at SEMICON Taiwan**

*Advanced APS2 measurement technology incorporates a wider range of particle sizes in sensors that speeds processes and improves yields*

**Minneapolis, MN—Aug. 15<sup>th</sup>, 2016—** [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces it will showcase its next-generation Airborne Particle Sensor technology (APS2), that incorporates large particle sensing capability. Both the WaferSense® and ReticleSense® Airborne Particle Sensors (APS2, APSR and APSRQ) can measure both small and large particles. The new large particle detecting and measurement functionality covers a range of sizes with four bins for particles larger than 2, 5, 10 and 30 microns. Products will be on display at the upcoming [SEMICON Taiwan](#) in Taipei, September 7-9, 2016 in booth #200, 4<sup>th</sup> floor.

CyberOptics' APS2 portfolio speeds equipment set-up and long-term yields in semiconductor fabs by wirelessly monitoring airborne particles in real-time. The next-generation APS2 provides even greater versatility, with the industry-leading accuracy and sensitivity valued by semiconductor fabs and equipment OEMs worldwide.

“We’ve taken the Best Known Method for wireless particle measurement in semiconductor fabs and made it even better,” said Ferris Chen, Director of Sales, CyberOptics, Asia. “We’ve extended the APS2 technology to include large particle measurement capability in the very same device that our customers use to save time, save expense and improves yields.”

At SEMICON Taiwan, CyberOptics will also demonstrate its WaferSense and ReticleSense Auto Multi Sensors (AMS/AMSR) that measure leveling, vibration, and relative humidity (RH) in an all-in-one wireless real-time device. The thin and light form factor enables the AMS to travel through virtually any tool and the AMSR can capture multiple measurements in all locations of the reticle environment. The all-in-one devices are yet another way to increase yield and reduce downtime in semiconductor environments.

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### **About the WaferSense and ReticleSense Line**

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm and 300mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding our 2014 acquisition of Laser Design, Inc. (LDI) and its impact on our operations; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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